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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Michael GANSER et al.  
Title: METHOD AND APPARATUS FOR LASER  
MICRODISSECTION  
Appl. No.: 09/943,093  
Appl. Filing Date: 8/31/01  
Examiner: Louise Leary  
Art Unit: 1654

TECH CENTER 1650/2000

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**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination of the present, Applicants respectfully request that the above-identified application be amended as follows:

**In the Specification:**

**On page 3, delete the last paragraph, and replace this paragraph with the following in accordance with 37 CFR §1.121. A marked up version showing changes is attached:**

A1

It is a further object of the invention to provide an apparatus for laser microdissection which allows a sample field to be reliably cut out of a specimen, and which dispenses with any defocusing of the laser beam to carry off the specimen.

**On page 10, delete the first paragraph, and replace this paragraph with the following in accordance with 37 CFR §1.121. A marked up version showing changes is attached:**

A2

To prepare for the cutting operation, a narrow cut width of laser beam 7 is then set. During cutting, X-Y stage 2 is then displaced in steps in such a way that laser beam 7 successively strikes the calculated reference position(s) on specimen 4, the